

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S24	70	(chip semiconductor) with (thin\$3 thick\$3) with (inn\$3) and (inn\$3) with taper\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 13:44
S25	18912	((257/666-677,E23.031-E23.059) or (257/E23.004,E23.043-E23.05) or (257/E23.005-E23.009) or (257/E23.041,E23.053-E23.055)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/17 13:44
S27	747	S26 and (lead near3 frame leadframe lead-frame) with (thick\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 13:59
S28	4	("20050093117").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/05/17 13:59
S26	10664	S25 and (lead near3 frame leadframe lead-frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:26
S29	86723	(lead near3 frame leadframe lead-frame)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:26
S30	14044	S29 and (resin with (mold\$3 encapsulat\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:27

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S31	9230	S30 and (wir\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:27
S32	9230	S31 and (((@ad<"20030411") or (rlad<"20030411"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:29
S33	60	S32 and (chip semiconductor adj device die) with (thick\$3) with (inner near2 lead)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 16:32
S34	228	S32 and (chip semiconductor adj device die) with (thin\$3) with (inner near2 lead)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 17:10
S35	1652	S32 and (stack\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 17:10
S36	749	S35 and (inner and outer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 17:10